

AMENDMENTS TO THE CLAIMS:

Applicants propose amending claim 21, as indicated below. This listing of claims will replace all prior versions and listings of claims in the application:

LISTING OF CLAIMS:

1.-12. (Cancelled)

13. (Previously Presented) A method for manufacturing a mold tool adapted to be used for forming a structured nano scale pattern on an object and having a layer, which is anti-adhesive with regard to the object, said method comprising the following steps:

providing a stamp blank with a structured pattern on a surface,

depositing a layer of a metal chosen from titanium, zirconium, niobium, tantalum, and aluminium, and mixtures thereof, on the patterned surface, said metal having a stable oxidation number,

oxidising the layer of metal to form a mechanically stable oxide film, and

applying at least one reagent on the oxide film, said reagent comprising molecule chains, each having a linkage group, which is chemically bonded with the oxide film, wherein the molecule chains either from the beginning comprise at least one group comprising fluorine, or are provided with at least one such group in a subsequent treatment.

14. (Previously Presented) The method of claim 13 wherein said linkage group is chemically bonded by a covalent bond with said oxide film.

15. (Cancelled)

16. (Previously Presented) The method according to claim 13, wherein said linkage group is chosen among silane groups, phosphate groups and carboxylic groups.

17. (Previously Presented) The method according to above claim 13, wherein the metal is furnished to the pattern equipped surface in an evaporated form.

18. (Previously Presented) The method according to above claim 13, wherein the layer of metal is oxidised by bringing it in contact with a gas comprising oxygen, such as surrounding air, filtered surrounding air, or a synthetical gas mixture comprising oxygen.

19. (Previously Presented) The method according to claim 13, wherein the patterned surface is coated with a layer of metal with a thickness (HT) of 1-300 nm.

20. (Previously Presented) The method according to any one of claims 13, 14, 16, and 17, wherein the patterned surface is coated with a layer of metal with a thickness (HT) of 1-100 nm.

21. (Currently Amended) A mold tool adapted to be used for forming a structured nano scale pattern on an object, comprising:

a stamp blank having a structured pattern on its surface,

a layer of metal disposed on the surface, the layer of metal comprising at least one of aluminium, zirconium, tantalum, niobium, and titanium,

a mechanically stable oxide film on the layer of metal, the oxide film comprising an oxide of said at least one of aluminium, zirconium, tantalum, niobium, and titanium, wherein the oxide film is formed by oxidizing the metal layer, and

an anti-adhesive layer, which is anti-adhesive with regard to the object, comprising at least one reagent on the oxide film, said reagent comprising molecule chains, each having at least one linkage group and at least one group comprising fluorine, [[and]] which is chemically bonded with the oxide film, and wherein the molecule chains either from the beginning comprise at least one group comprising fluorine, or are subsequently provided with at least one such group

a layer of metal disposed intermediate to the stamp blank and the anti-adhesive layer, the layer of metal comprising at least one of aluminium, zirconium, tantalum, niobium, and titanium, the layer of metal being oxidised to form a mechanically stable oxide film to which the at least one linkage group is chemically bonded.

22. (Previously Presented) The mold tool according to claim 21 wherein said at least one linkage group is chemically bonded by a covalent bond with said oxide film.

23. (Previously Presented) The mold tool according to claim 21, wherein said layer of metal has a thickness (HT) of 1-300 nm.

24. (Previously Presented) The mold tool according to claim 21, wherein said layer of metal has a thickness (HT) of 1-100 nm.

25. (Previously Presented) The mold tool according to claim 21, wherein said stamp blank comprises a metal and/or silicon.

26. (Previously Presented) The mold tool according to claim 25, wherein said stamp blank comprises nickel.

27.-28. (Cancelled)